

On page 1, line 5, change "Dr. Richter" to --H. Richter-- and change "referred to and discussed at the end" to --"Chips mit Zukunftspotential" [Chips with Future Potential], interim results of the Telekom Research Project OEIC, Telekom Vision 7/93, pp. 41 through 47, which is hereby incorporated by reference herein--.

On page 2, line 15, before "path" insert --circuit--.

On page 2, line 18, before "DE" insert --No.--.

On page 2, line 19, change "EP 0 779 526" to --No. EP 0 779 526, which are hereby incorporated by reference herein--.

On page 2, line 21, change "this publication" to --European Patent No. EP 0 779 526--

On page 2, line 27, before both occurrences of "DE" insert --No.--.

On page 2, line 29, change "already explained" to --noted above--.

On page 3, before line 1, insert --Summary of the Invention--.

On page 3, line 1, change "The object" to --An object-- and change "devise" to --provide--.

On page 3, delete lines 7-11.

On page 3, before line 13, insert --The present invention provides a semiconductor laser including a semiconductor laser chip and at least one temperature sensor disposed directly on or integrated in the semiconductor laser chip for measuring an operating temperature.--.

On page 3, line 24, after "are" insert --revealed below--.

On page 3, delete lines 25-28.

On page 3, before line 30, insert --Brief Description of the Drawings--.

On page 3, line 30, before "invention" insert --present--, delete "now" and change "on the basis of exemplary embodiments. In the" to --with reference to the drawings, in which--.

On page 4, delete line 1.

On page 4, line 3, after "Figure 1" insert --a schematic diagram of--.

On page 4, line 5, after "Figure 2" insert --a schematic diagram of--.

On page 4, line 8, after "Figure 3" insert --a schematic diagram of--.

On page 4, line 10, after "Figure 4" insert --a schematic diagram of--.

On page 4, line 13, after "Figure 5a" insert --a schematic diagram of--.

On page 4, line 15, after "Figure 5b" insert --a schematic diagram of--.
On page 4, line 17, after "Figure 6" insert --a schematic diagram of--.
On page 4, line 20, after "Figure 7" insert --a schematic diagram of--.
On page 4, line 23, after "Figure 8" insert --a schematic diagram of--.
On page 4, line 26, after "Figure 9" insert --a schematic diagram of--.
On page 4, line 28, after "Figure 10" insert --a schematic diagram of--.
On page 4, line 30, after "Figure 11" insert --a schematic diagram of-- and change
"thermo-" to --thermoelement--.

24 note On page 5, line 1, before "Peltier" insert --a--. *not entered*

On page 5, line 3, after "Figure 12" insert --a schematic diagram of--.

On page 5, line 5, after "Figure 13" insert --a schematic diagram of--.

On page 5, before line 7, insert --Detailed Description--.

On page 5, line 7, change "in the" to --in H. Richter, "*Chips mit Zukunftspotential*"

97 [Chips with Future Potential], discussed above--.

On page 5, delete lines 8-9.

On page 5, line 10, delete "pp. 41 through 47." and change "only" to --typically--.

On page 6, line 12, after "Patent" insert --No. DE--.

On page 8, line 11, change "must be" to --is--.

On page 9, line 10, change "the main application case" to --an embodiment--.

On page 9, line 12, before "measurement" insert --for--.

On page 9, line 14, before "measurement" insert --for--.

On page 9, line 22, change "12 -, to" to --12 - to--.

On page 11, line 1, change "Patent Claims" to --WHAT IS CLAIMED IS:--.

IN THE CLAIMS

Please cancel without prejudice claims 1-15 and add new claims 16-33 as follows:

A8
Contd
Sub B17

--16. (new) A semiconductor laser comprising:
a semiconductor laser chip; and
at least one temperature sensor disposed directly on or integrated in the semiconductor